

REFERENCE TABLE

Our reference table offers you a survey of the drying times of your components. Please read it dependent on component strength, MSL Level, temperature and humidity Level.

MSL level	Drying at 1% RH <i>(HSD, MSD & XSD-Series)</i>			Drying at 2% RH <i>(SDB, SD, SD+ & ESDA Serie)</i>		**Drying at 5% RH <i>(N²-Cabinets)</i>		
	25°C 1% RH	40°C 1% RH	60°C 1% RH	25°C 2% RH	40°C 2% RH	40°C 5% RH	90°C 5% RH	
Body thickness ≤ 1,4 mm	2	3 days	36 hours	10 hours	8 days	3 days	8 days	17 hours
	2a	4 days	2 days	12 hours	9 days	4 days	9 days	23 hours
	*3	8 days	3 days	18 hours	12 days	5 days	13 days	33 hours
	4	9 days	4 days	24 hours	15 days	6 days	15 days	37 hours
	5	10 days	5 days	30 hours	17 days	7 days	17 days	41 hours
	5a	10 days	6 days	36 hours	22 days	9 days	22 days	54 hours
Body thickness ≤ 2,0 mm	2	18 days	8 days	2 days	25 days	10 days	25 days	63 hours
	2a	22 days	10 days	2 days	30 days	15 days	29 days	3 days
	3	23 days	11 days	2 days	35 days	16 days	37 days	4 days
	4	28 days	14 days	3 days	40 days	17 days	47 days	5 days
	5	35 days	16 days	4 days	50 days	24 days	57 days	6 days
	5a	56 days	18 days	4 days	67 days	27 days	79 days	8 days
Body thickness > 2,0 mm ≤ 4,5 mm	2	67 days	20 days	5 days	80 days	30 days	79 days	10 days
	2a	67 days	22 days	5 days	80 days	30 days	79 days	10 days
	3	67 days	22 days	5 days	80 days	31 days	79 days	10 days
	4	67 days	22 days	5 days	80 days	31 days	79 days	10 days
	5	67 days	22 days	5 days	80 days	31 days	79 days	10 days
	5a	67 days	22 days	5 days	80 days	31 days	79 days	10 days

* according 100TQFP-Test (Semiconductor Device (100TQFP) Dehumidifying Property)

** according to IPC J-STD-033C